China Semiconductor Technology International Conference (CSTIC) 2020 Summary
June 26-July 24
2020 CSTIC - First Online Virtual Conference

- Largest and most comprehensive, influential annual industrial semiconductor technology conference in China and Asia
- Record-breaking 430 abstracts, 2746 attendees, and 12630 clicks at v.semi.org.cn
220 Full-Length Manuscripts Published in IEEE Xplore (EI cited)
International Collaboration

- 430 submissions from 17 countries and regions

![Diagram showing international collaboration](chart.png)

- Mainland China: 70%
- US: 13%
- Japan: 4%
- Korea: 2%
- HK, Macao: 1%
- Taiwan, China: 3%
- Malaysia, Singapore: 1%
- France, Netherlands, Germany, Italy, Sweden: 6%
- Others: 18%
Industry Collaboration

- 63% abstracts from industry
Registration Worldwide

2746 registration from 20 countries and regions

Belgium
Canada
China Hong Kong
China Macau
China Mainland
China Taiwan Region
Finland
France
Germany
Italy
Japan
Korea
Malaysia
Netherlands
Singapore
South Africa
Sweden
Switzerland
United Kingdom
United States of America
Plenary Keynotes

Next Big Frontiers - Chiplet Integration and More
Dr. Doug Yu
Vice President, R&D, TSMC

EUV Lithography - the Road to High-Volume Manufacturing
Dr. Anthony Yen
Vice President, ASML

Opportunities in Advanced Packaging for Heterogeneous Integration
Dr. Ravi Mahajan
Fellow, Intel

Integrated Materials Solutions: A Path Forward For Moore's Law
Dr. Sanjay Natarajan
Vice President, Applied Materials
Conference Schedule

Poster Session: June 26-July 24  
156 posters

Tutorials: June 28-July 24  
5 tutorials

Plenary Session, 9 Symposia and Panel Discussion  
157 videos

Symp I: Device Engineering and Memory Technology

Symp. II: Lithography and Patterning

Symp. III: Dry & Wet Etch and Cleaning

Symp. IV: Thin Film, Plating and Process Integration

Symp. V: CMP and Post-Polish Cleaning

Symp. VI: Metrology, Reliability and Testing

Symp. VII: Packaging and Assembly

Symp. VIII: MEMS, Sensors and Emerging Semiconductor Technologies

Symp. IX: Design and Automation of Circuits and Systems
Panel Discussion: System Integration through 3D and Advanced Packaging

1. We understand that 3D heterogeneous integration will help extend Moore’s law from systems’ perspective. Will it be a short-term boost or continuous enhancement node after node?

2. What are the key features for 3D and Advance Packaging Integration, TSV pitch, Chip Layers, etc? How small these critical pitches can go and is there a trend like Moore’s law to follow?

3. 3D package vs. 3D sequential integration comparison in terms of thermal budgets, performance, power management, etc.

4. What are the impacts of the 3D and Advance Packaging Integration to the existing OSAT business and supply chains? What are the major opportunities for the existing OSAT business?

Panelists

Dr. Doug Yu
Vice President, R&D, TSMC

Dr. Ravi Mahajan
Fellow, Intel

Dr. Bill Bottoms
CEO, 3MTS
Tutorials

1. Advanced Memory Technologies: MRAM
   Dr. Shu-Jen Han
   Senior Director
   HFC Semiconductor Corp.

2. Advanced Memory Technologies: EPCM/3D-PCM
   Dr. Yu Zhu
   Executive Assistant to CEO,
   Jiangsu Advanced Memory Semiconductor (AMS) Co., Ltd

3. Semiconductor Testing Solutions in the Trend of 5G and AI
   Liang Ge
   R&D manager and Test strategy leader
   Advantest China

4. Heterogeneous Integration And Advanced Packaging
   Dr. Bill Bottoms
   Chairman and CEO, 3MTS

5. IC Reliability Tests For 5G Applications
   Xu Feng
   Deputy General Manager & Technology Director
   JCET quality test center
Plenary Session and Award Winners
Conference Chair and Co-Chairs

Dr. Steve X. Liang
Chair
JCET, China

Dr. Qinghuang Lin
Exe. Co-Chair
Lam, USA

Dr. Ru Huang
Co-Chair
PKU, China

Dr. Cor Claeys
Co-Chair
KU Leuven, Belgium

Dr. Hanming Wu
Co-Chair
Zhejiang University
China
Symposium Chairs

Dr. Ru Huang
Chair, S-I
Peking Univ.
China

Dr. Kafai Lai
Chair, S-II
IBM
USA

Dr. Ying Zhang
Chair, S-III
Naura
USA

Dr. Zhong Zhang
Chair, S-IV
HFC. China

Dr. Xin Ping Qu
Chair, S-V
Fudan Univ.
China

Dr. Peilin Song
Chair, S-VI
IBM
USA

Dr. Steve X.
Chair, S-VII
Liang
JCET, China

Dr. Qinghuang
Chair, S-VII
Lin
Lam, USA

Dr. Wenjian Yu
Chair S-IX
Tsinghua
University, China

Dr. Hsiang-Lan
Poster Chair
Lung
Macronix,
Taiwan, China
Organizing Team

Mr. Lung Chu
President
SEMI China

Ms. Lily Feng
Ms. April Peng
Ms. Cheryl Qiu
Ms. Mina Chen
Mr. Tony Liu

Mr. Jesse Zhang
Ms. June Wu
Mr. Mortal Li
Ms. Hannah Zhao
Ms. Louisa Li

Dr. Lode Lauwers
Vice President
IMEC, Belgium
Special Thanks to Sponsors
CSTIC 2021

• Time: March 14-15 (Sunday-Monday)

• Venue: Shanghai International Convention Center (SHICC)

• Call for Papers Deadline: Nov. 15, 2020
Thanks for the Support!